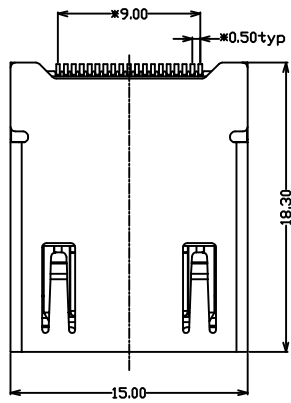
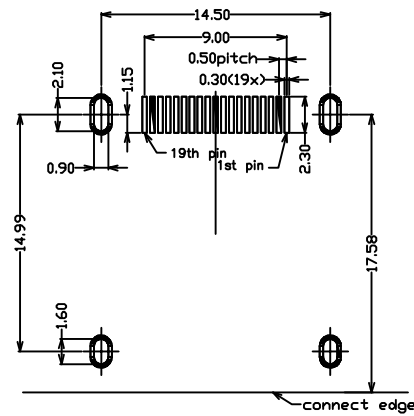


1 2 3 4 5 6 7

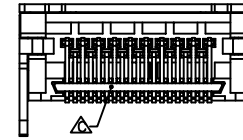
A



B



RECOMMENDED P.C.B LAYOUT
(THICKNESS=1.60±0.05mm)

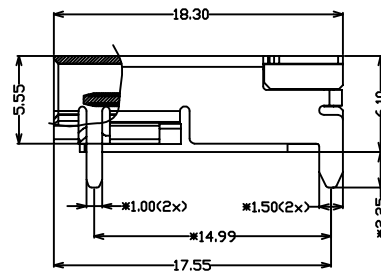
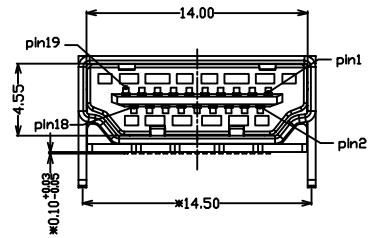


A

B

PART NO.	PIN PLATING	PLATING
70109-TF1A	GOLD(15u ²)/TIN PLATED	鍍銀
70109-TF1B	GOLD(5u ²)/TIN PLATED	鍍銀
70109-TF1C	GOLD(5u ²)/TIN PLATED	鍍銀
70109-TF1D	GOLD(1u ²)/TIN PLATED	鍍銀

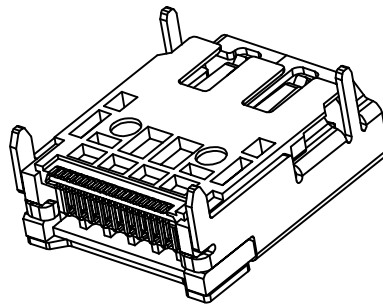
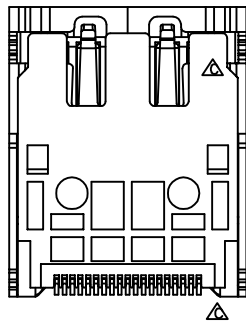
C



C

Specification
 1.Electrical Characteristics:
 Contact Current Rating: 0.5 Amperes.
 Dielectric Withstanding Voltage: AC 500V r.m.s.
 Insulation Resistance: 100MΩ Min.
 Contact Resistance: 30mΩ Max.
 2.Mechanical Characteristics:
 Contact Insertion Force: 4.5Kg Maximum.
 Contact Separation Force: 1.0~4.0Kg
 3.Environmental:
 Operating Temperature: -55°C~+105°C.
 4.Material:
 Insulator: HI-Temp Plastic UL 94V-0.
 Contact: Copper Alloy (t=0.20mm).
 Shell: Copper Alloy (t=0.50mm).
 5.PLATING:
 TERMINAL: Au plated on contact point
 100u² Sn plated on solder tail point
 both over 50u² Min Ni underplated overall
 SHELL: 50u² solder base Ni overall.
 6.Solder-ability: 260±5°C for 5.0±0.5 sec
 7.*不是重點管理尺寸

D



D

E

1 2 3 4 5 6 7

尚益科技有限公司
JMSCONN TECHNOLOGY CO., LTD.

PROJ	SCALE : F DO NOT SCALE DWG	MOLD NO	70109-T		
APP		MODEL	FILE NO	REV. X1	
CHK		UNIT	SHT 1 OF 1	SIZE A4	
DGN		MM			
DRW	HSIEH	2012.05.20			

E